

Features

- Uses PingWei advanced PerfectMOS2 technology
- Extremely low on-resistance $R_{DS(on)}$
- Excellent $Q_g \times R_{DS(on)}$ product(FOM)
- Excellent Low Ciss
- Qualified according to AEC-Q101 criteria

Benefits

- High robustness and reliability
- Increases maximum current capability
- Low power loss, high power density
- Easy paralleling



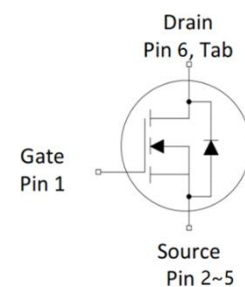
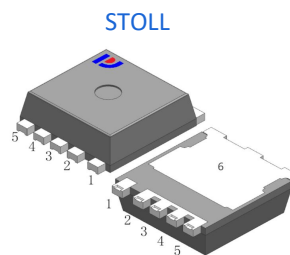
100% DVDS Tested
100% Avalanche Tested

Applications

- General automotive applications
- Motor Drivers
- General SMPS devices

Product Summary

V_{DS}	100V
$R_{DS(on)}@10V$ typ	2.1mΩ
I_D	150A

**Package Marking and Ordering Information**

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
PWC026N10USQ	C026N10USQ	STOLL	Tape&Reel	13 inches	16mm	1800pcs

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	100	V
Continuous drain current $T_C = 25^\circ\text{C}$ (Silicon limit) $T_C = 25^\circ\text{C}$ (Package limit) $T_C = 100^\circ\text{C}$ (Silicon limit) $T_a = 25^\circ\text{C}$ (Note 1)	I_D	198 150 140 24	A
Pulsed drain current ($T_C = 25^\circ\text{C}$, $t_p = 100\mu\text{s}$)	$I_{D \text{ pulse}}$	600	A
Avalanche energy, single pulse ($L=0.5\text{mH}$)	E_{AS}	471	mJ
Gate-Source voltage	V_{GS}	± 20	V
Power dissipation $T_C = 25^\circ\text{C}$ $T_a = 25^\circ\text{C}$ (Note 1)	P_{tot}	222 3.3	W
Operating junction and storage temperature	T_j, T_{stg}	-55...+175	$^\circ\text{C}$
Soldering temperature, wave soldering only allowed at leads (1.6mm from case for 10s)	T_{sld}	260	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Thermal resistance, junction – case.	RthJC	-	-	0.68	°C/W	-
Thermal resistance, junction - ambient(min. footprint)	RthJA	-	-	46	°C/W	Note 1

Electrical Characteristic (at Tj = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV _{DSS}	100	-	-	V	V _{GS} =0V, I _D =250μA
Gate threshold voltage	V _{GS(th)}	2	-	4	V	V _{DS} =V _{GS} , I _D =250μA
Zero gate voltage drain current	I _{DSS}	-	-	1 100	μA	V _{DS} =100V, V _{GS} =0V T _j =25°C T _j =150°C
Gate-source leakage current	I _{GSS}	-	-	±100	nA	V _{GS} =±20V, V _{DS} =0V
Drain-source on-state resistance	R _{DS(on)}	-	2.1	2.6	mΩ	V _{GS} =10V, I _D =30A
Transconductance	g _{fs}	-	94	-	S	V _{DS} =5V, I _D =30A

Dynamic Characteristic

Input Capacitance	C _{iss}	-	4986	-	pF	V _{GS} =0V, V _{DS} =50V, f=1MHz
Output Capacitance	C _{oss}	-	1829	-		
Reverse Transfer Capacitance	C _{rss}	-	62	-		
Gate Total Charge	Q _G	-	73	-	nC	V _{DS} =50V, I _D =30A, V _{GS} =10V
Gate-Source charge	Q _{gs}	-	25	-		
Gate-Drain charge	Q _{gd}	-	15	-		
Turn-on delay time	t _{d(on)}	-	23	-	ns	V _{GS} =10V, V _{DD} =50V, R _{G_ext} =1.6Ω, I _D =25A
Rise time	t _r	-	32	-		
Turn-off delay time	t _{d(off)}	-	52	-		
Fall time	t _f	-	19	-		
Gate resistance	R _G	-	1.8	-	Ω	V _{GS} =0V, V _{DS} =0V, f=1MHz

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	-	1.2	V	$V_{GS}=0V, I_{SD}=30A$
Body Diode Continuous Forward Current	I_S	-	-	150	A	TC = 25°C
Body Diode Pulsed Current	I_S pulse	-	-	600	A	TC = 25°C, $t_p = 100\mu s$
Body Diode Reverse Recovery Time	t_{rr}	-	80	-	ns	$I_F=30A,$ $dI/dt=100A/\mu s$
Body Diode Reverse Recovery Charge	Q_{rr}	-	70	-	nC	

Note 1: 1 inch², single 2oz copper FR-4 PCB.

Typical Performance Characteristics

Fig 1: Output Characteristics

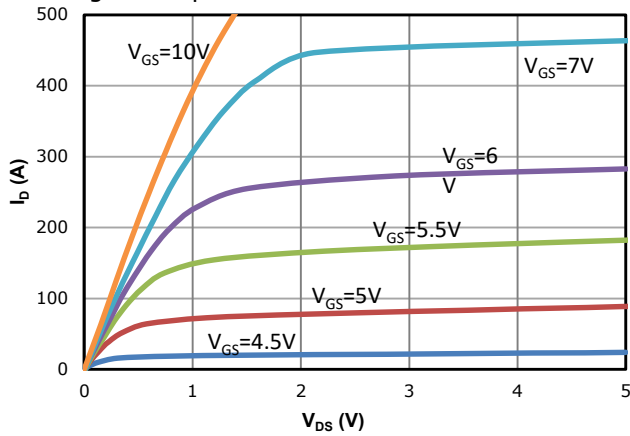


Fig 2: Transfer Characteristics

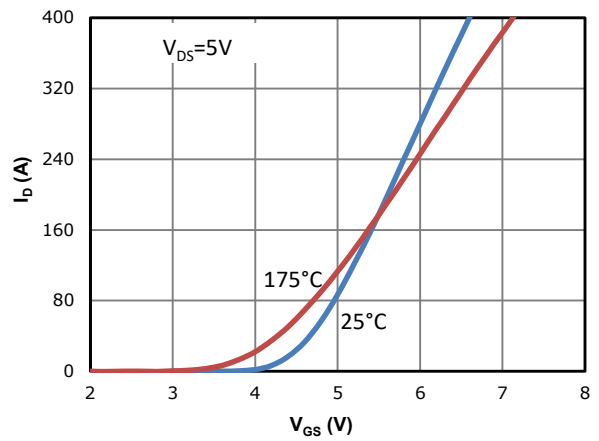


Fig 3: Rds(on) vs Drain Current and Gate Voltage

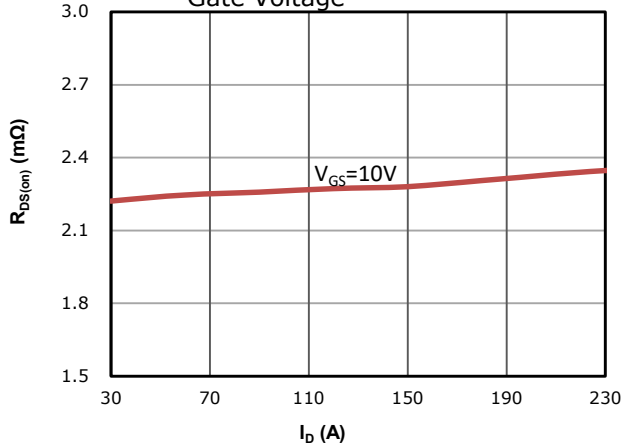


Fig 4: Rds(on) vs Gate Voltage

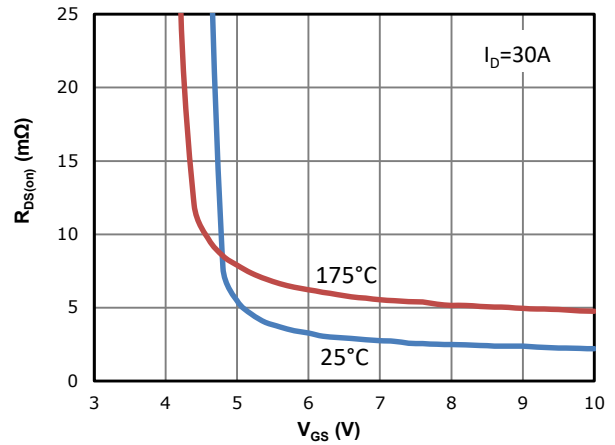


Fig 5: Rds(on) vs. Temperature

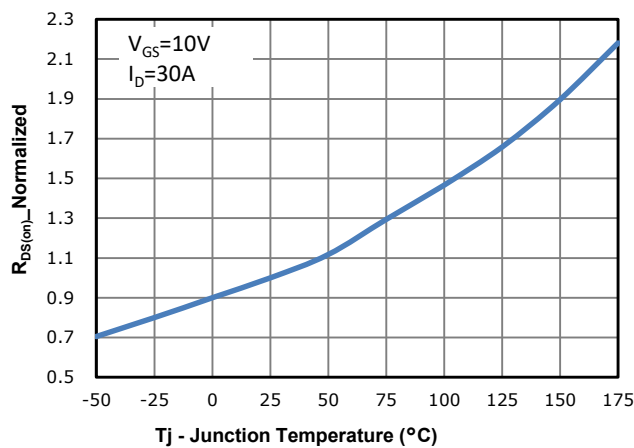


Fig 6: Vgs(th) vs. Temperature

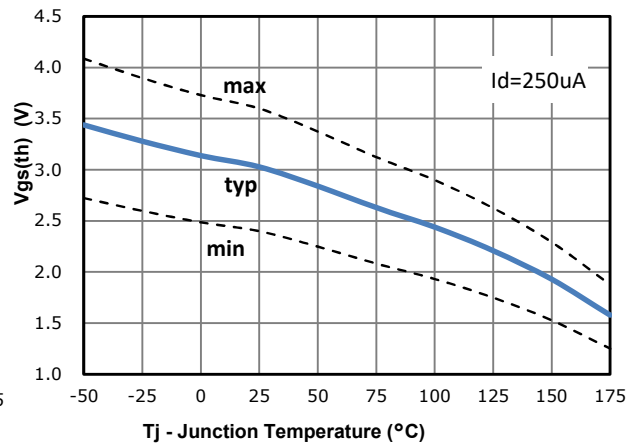


Fig 7: BV_{dss} vs. Temperature

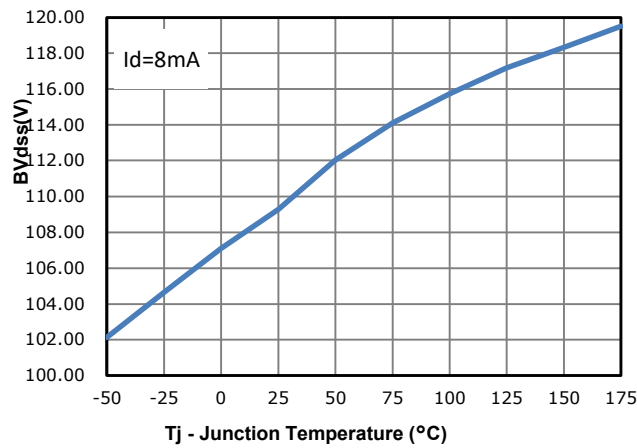


Fig 8: Capacitance Characteristics

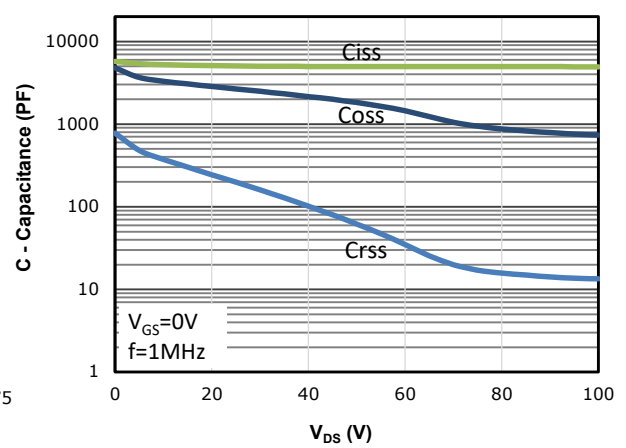


Fig 9: Gate Charge Characteristics

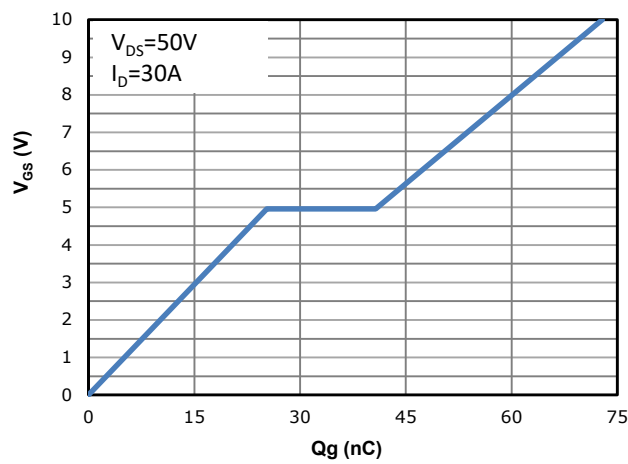


Fig 10: Body-diode Forward Characteristics

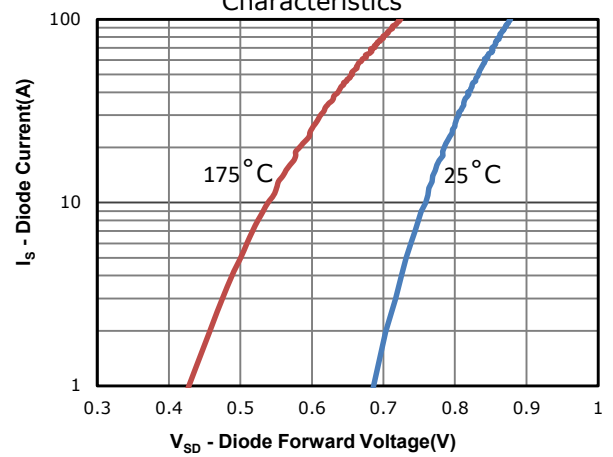


Fig 11: Power Dissipation

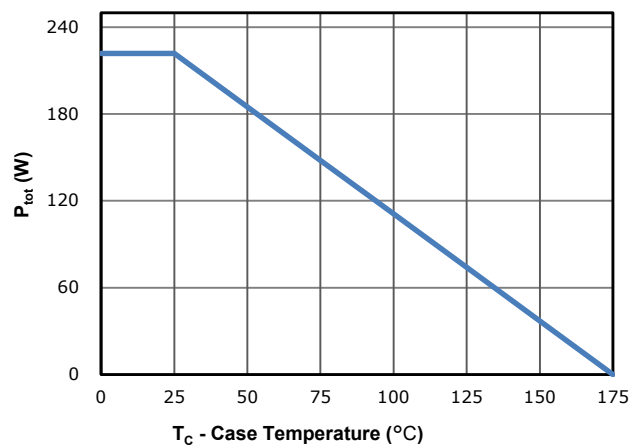


Fig 12: Drain Current Derating

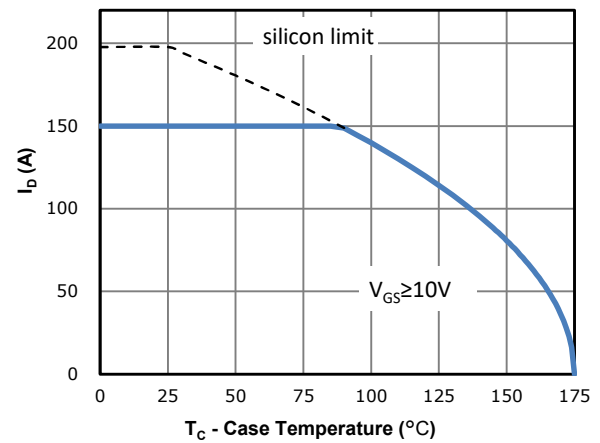


Fig 13: Safe Operating Area

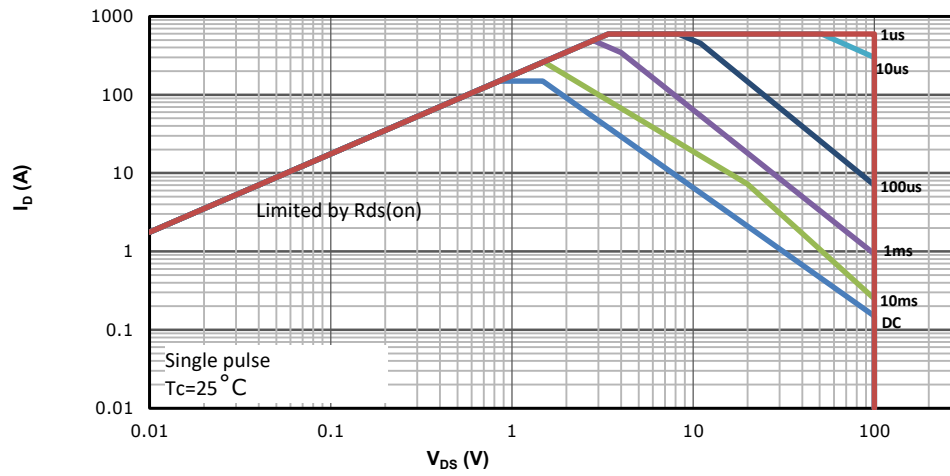
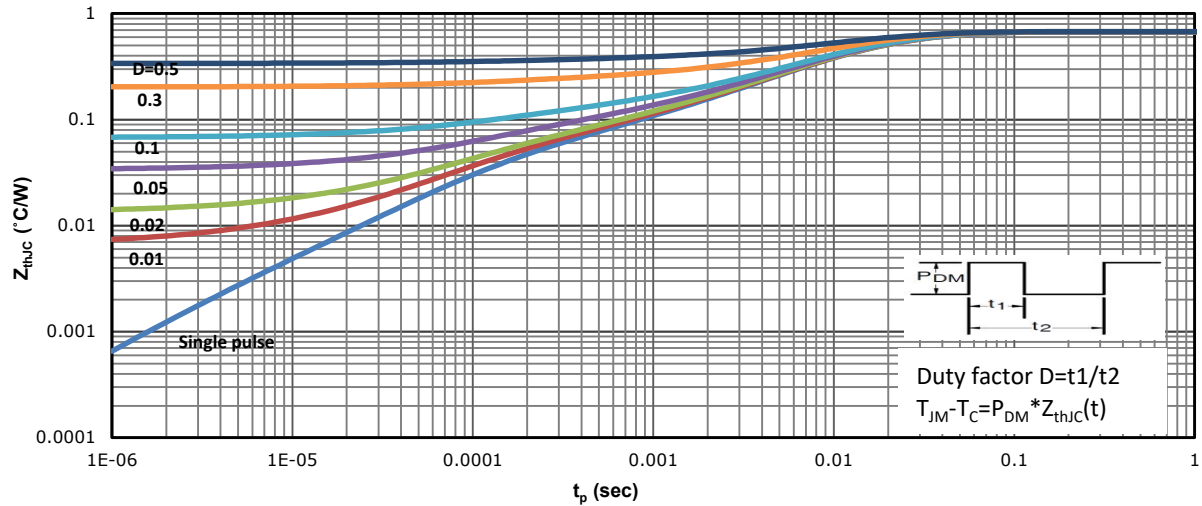
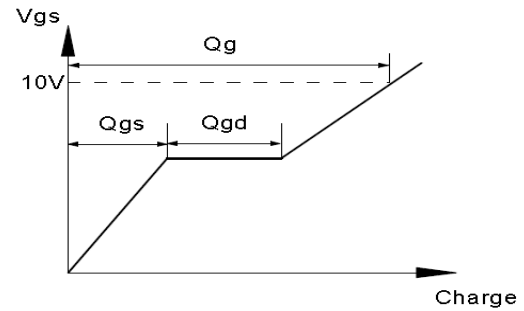
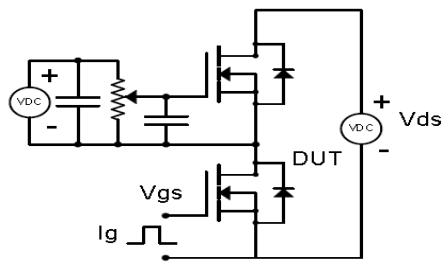


Fig 14: Max. Transient Thermal Impedance

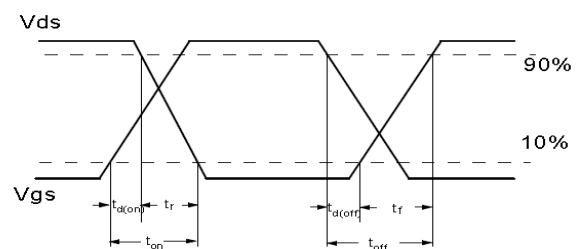
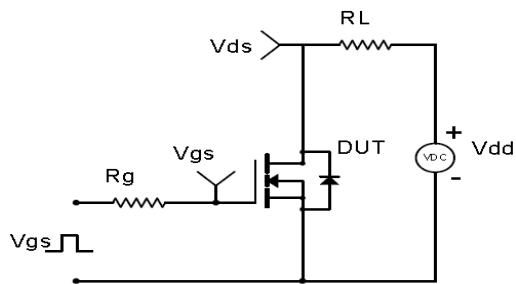


Test Circuit & Waveform

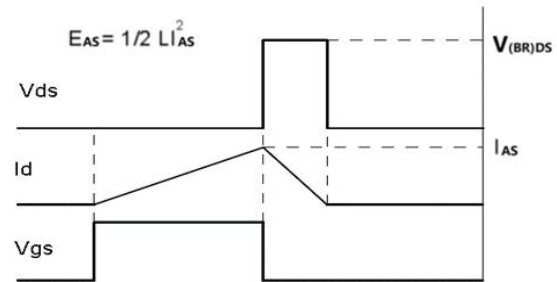
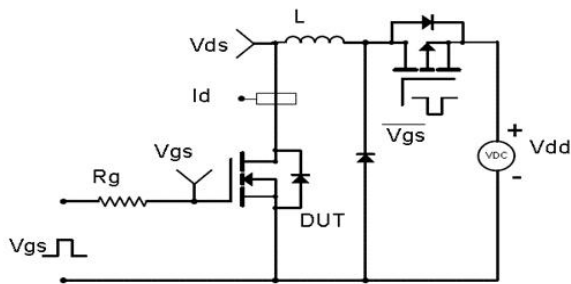
Gate Charge Test Circuit & Waveform



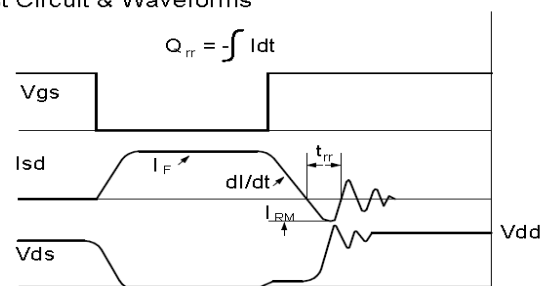
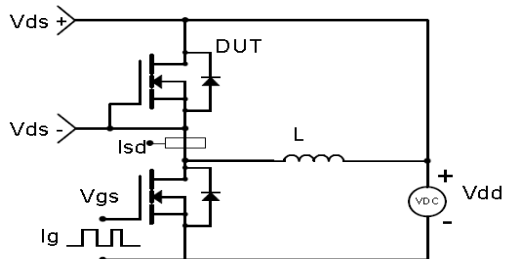
Resistive Switching Test Circuit & Waveforms

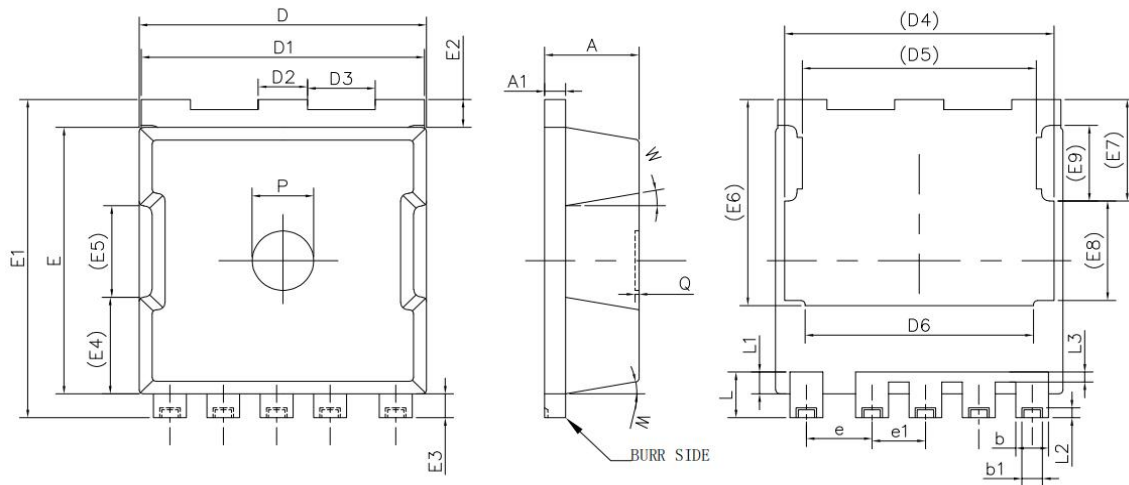


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Outline: STOLL

SYMBOL	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.20	2.40	0.087	0.094
A1	0.40	0.60	0.016	0.024
b	0.70	0.90	0.028	0.035
b1	0.40	0.60	0.016	0.024
D	6.80	7.20	0.268	0.283
D1	6.80	7.20	0.268	0.283
D2	1.10	1.30	0.043	0.051
D3	1.55	1.75	0.061	0.069
D4	6.56		0.258	
D5	5.70		0.224	
D6	5.56		0.219	
E	6.50	6.90	0.256	0.272
E1	7.80	8.20	0.307	0.323
E2	0.60	0.80	0.024	0.031
E3	0.50	0.70	0.020	0.028
E4	2.43		0.096	
E5	2.30		0.091	
E6	5.18		0.204	
E7	2.55		0.100	
E8	2.50		0.098	
E9	1.90		0.075	
e	1.60		0.063	
e1	1.30		0.051	
L	1.05	1.25	0.041	0.049
L1	0.40	0.70	0.016	0.028
L2	0.15	0.35	0.006	0.014
L3	0.15	0.35	0.006	0.014
P	1.40	1.60	0.055	0.063
Q	0.00	0.10	0.000	0.004
W	8°	11°	8°	11°

Revision History

Revision	Date	Major changes
1.1	2025/6/11	Update Rja max & Zth &SOA

Disclaimer

Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

The product is not intended for use in applications that require extraordinary levels of quality and reliability, such as aviation/aerospace and life-support devices or systems.

Buyer is responsible for its products and applications using PingWei products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by PingWei.

"Typical" parameters which may be provided in PingWei data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts

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